

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently amended) A soldering workpiece made from aluminum and/or aluminum compounds, having an oxide and/or hydroxide layer arranged at a surface of the soldering workpiece, ~~characterized in that~~ wherein the thickness d of the oxide and/or hydroxide layer is greater than the thickness of a native oxide and/or hydroxide layer.
2. (Currently amended) The soldering workpiece as claimed in claim 1, ~~characterized in that~~ wherein $25\text{ nm} < d < 1000\text{ nm}$, in particular $50\text{ nm} < d < 500\text{ nm}$, in particular $80\text{ nm} < d < 250\text{ nm}$.
3. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims,~~ claim 1, wherein the oxide and/or hydroxide layer consists predominantly of boehmite.
4. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims,~~ claim 1, wherein the oxide and/or hydroxide layer includes inhomogeneities, in particular notches, pores and/or cracks.
5. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims,~~ claim 1, wherein the homogeneities are introduced into the oxide and/or hydroxide layer by chemical and/or thermal and/or mechanical treatment of the soldering workpiece.
6. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims,~~ claim 1, wherein the soldering workpiece is provided with an in particular halogen-containing lubricant.

7. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein the lubricant includes additives or constituents such as carboxylic acids, amines, sulfur compounds and/or phosphorus compounds.
8. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein the soldering workpiece has a solder layer comprising an aluminum compound.
9. (Currently amended) The soldering workpiece as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein a base material of the soldering workpiece has a magnesium content of greater than 0.2%, in particular greater than 0.5%, preferably less than 2%.
10. (Currently amended) A soldering process for joining at least two workpieces to one another, ~~characterized in that~~ wherein at least one workpiece as described in ~~one of the preceding claims~~ claim 1 is used.
11. (Currently amended) A soldering process, in particular the soldering process as claimed in claim 10, with prior machining processes being carried out on at least one workpiece, in particular deep-drawing, cutting and/or punching, ~~characterized in that~~ wherein an in particular halogen-containing lubricant is applied to the workpiece during the prior machining processes.
12. (Currently amended) The soldering process as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein the lubricant includes additives or constituents such as carboxylic acids, amines, sulfur compounds and/or phosphorus compounds.

13. (Currently amended) The soldering process as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein thermal degreasing and the soldering operation are carried out together, in particular during a single heating operation.
14. (Currently amended) The soldering process as claimed in ~~one of the preceding claims, characterized in that~~ claim 1, wherein a shielding gas, in particular hydrogen, argon or nitrogen, is used for heating and/or soldering.
15. (Currently amended) A heat exchanger, in particular for a motor vehicle, ~~characterized in that~~ wherein the heat exchanger is at least partially soldered using the process as claimed in ~~one of the preceding claims~~ claim 1.